EXPEDITED PROCEDURE - EXAMINING GROUP 2818

PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Cheng-Yi Liu et al.

Examiner: Mai-Huong Tran

Serial No.:

10/036389

Group Art Unit: 2818

Filed:

January 7, 2002

Docket No.: 884.793US1

Title:

THINNED DIE INTEGRATED CIRCUIT PACKAGE

Assignee:

Intel Corporation

Customer No.: 21186

RESPONSE AFTER FINAL REJECTION UNDER 37 CFR § 1.116

Mail Stop AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Applicant has reviewed the Final Office Action mailed on November 28, 2003. Please consider the following remarks in regard to the above-identified patent application.

-Yi Liu et al.

INNED DIE INTEGRATED CIRCUIT PACKAGE

Docket No.:

884.793US1

Filed:

January 7, 2002

Examiner:

Mai-Huong Tran

Customer No.: 21186

Serial No.: 10/036389

Due Date: February 28, 2004

Group Art Unit: 2818 Confirmation No.: 3651

MS AF

Commissioner for Patents

.P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

A return postcard.

A Response to Final Rejection Under 37 CFR 1.116--Expedited Procedure (9 Pages).

Formal Drawings (10 pgs.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

Atty: Ann M. McCrackin Reg. No. 42,858

Kacea Lee

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 14 day of January, 2004.

Name

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

(GENERAL)